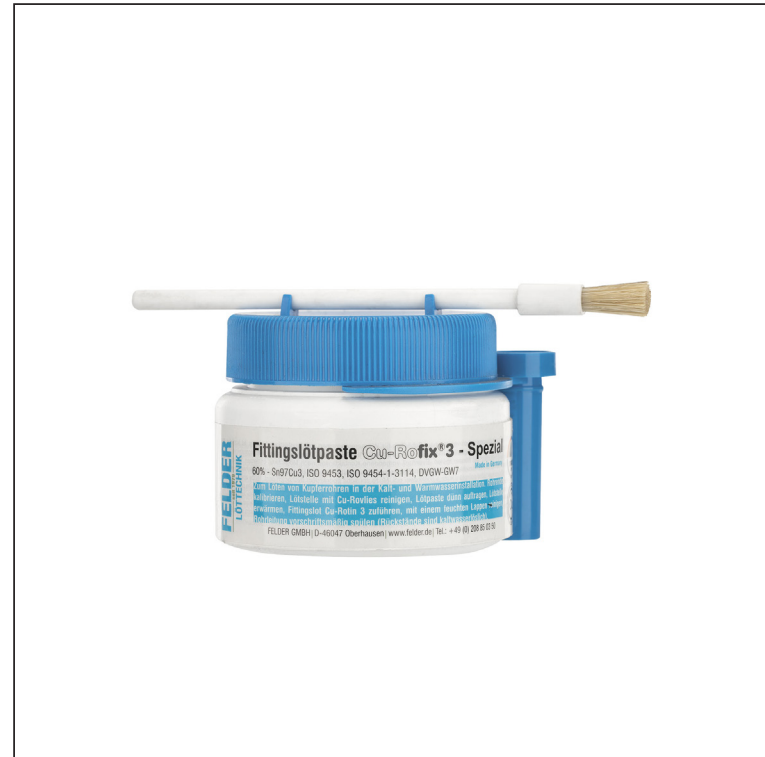


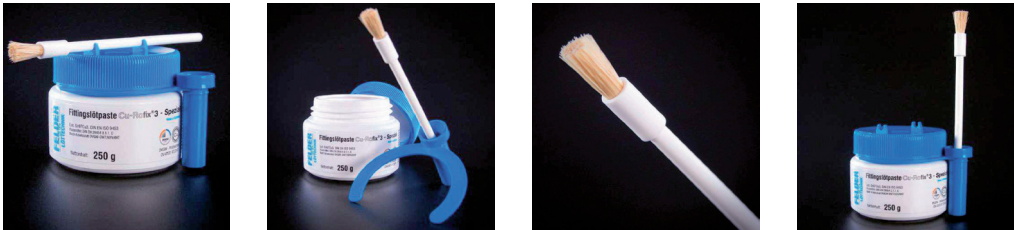
TECHNICAL SHEET

FITTING SOLDER PASTE

SCH-FELD ROFIX 250G



APPLICATION:



Technical parameter	
Application	finished soft solder paste for preliminary and soft soldering copper products
Melting Point	230 – 250 °C
Boiling Point	100 °C
Flash Point	135 °C
Weight	250 g/pcs

INDEX	CHANGE	DATE	SIGNATURE	KJG QUALITY ©	
MATERIAL BRAND			W.C.	WEIGHT kg	SCALE
SIZE, SEMI-FINISHED PRODUCTS				STN STANDARD	SORTING NUMBER
AUXILIARY EQUIPMENT				NOTE	POSITION NUMBER
ELABORATED BY Ing. Kluska M.					
TESTED BY				OLD DRAWING	DRAWING NUMBER
TECHNOLOGIST			TECHNOLOGIST		
NAME			Fitting solder paste		SCH-FELD ROFIX 250G
			Number of sheets		Sheet

Created: 19.04.2026 14:01:15

Technical changes reserved